# Quad Analog Switch/ Multiplexer/Demultiplexer

# **High-Performance Silicon-Gate CMOS**

The MC74VHC4066 utilizes silicon–gate CMOS technology to achieve fast propagation delays, low ON resistances, and low OFF–channel leakage current. This bilateral switch/multiplexer/demultiplexer controls analog and digital voltages that may vary across the full power–supply range (from  $V_{\rm CC}$  to GND).

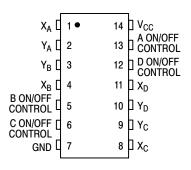
The VHC4066 is identical in pinout to the metal–gate CMOS MC14066 and the high–speed CMOS HC4066A. Each device has four independent switches. The device has been designed so that the ON resistances ( $R_{ON}$ ) are much more linear over input voltage than  $R_{ON}$  of metal–gate CMOS analog switches.

The ON/OFF control inputs are compatible with standard CMOS outputs; with pullup resistors, they are compatible with LSTTL outputs. For analog switches with voltage-level translators, see the VHC4316.

#### **Features**

- Fast Switching and Propagation Speeds
- High ON/OFF Output Voltage Ratio
- Low Crosstalk Between Switches
- Diode Protection on All Inputs/Outputs
- Wide Power–Supply Voltage Range  $(V_{CC} GND) = 2.0$  to 12.0 Volts
- Analog Input Voltage Range  $(V_{CC} GND) = 2.0$  to 12.0 Volts
- Improved Linearity and Lower ON Resistance over Input Voltage than the MC14016 or MC14066
- Low Noise
- Chip Complexity: 44 FETs or 11 Equivalent Gates
- These Devices are Pb-Free and are RoHS Compliant

#### **PIN ASSIGNMENT**





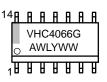
# ON Semiconductor®

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#### MARKING DIAGRAMS



SOIC-14 D SUFFIX CASE 751A





TSSOP-14 DT SUFFIX CASE 948G



A = Assembly Location

WL, L = Wafer Lot Y = Year WW, W = Work Week G or = Pb-Free Package

(Note: Microdot may be in either location)

#### **FUNCTION TABLE**

On/Off Control	State of
Input	Analog Switch
L	Off
H	On

#### ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
MC74VHC4066DR2G	SOIC-14 (Pb-Free)	2500 / Tape & Reel
MC74VHC4066DTR2G	TSSOP-14 (Pb-Free)	2500 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

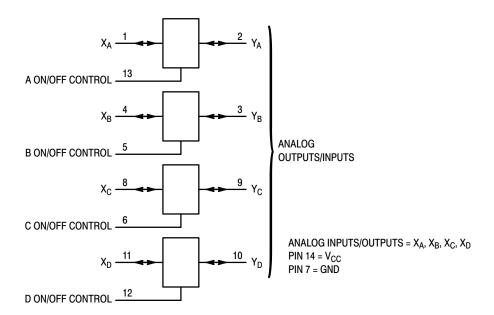


Figure 1. Logic Diagram

#### **MAXIMUM RATINGS**

Symbol	Parameter	Value	Unit
V <sub>CC</sub>	Positive DC Supply Voltage (Referenced to GND)	- 0.5 to + 14.0	V
V <sub>IS</sub>	Analog Input Voltage (Referenced to GND)	$-0.5$ to $V_{CC} + 0.5$	V
V <sub>in</sub>	Digital Input Voltage (Referenced to GND)	$-0.5$ to $V_{CC} + 0.5$	V
I	DC Current Into or Out of Any Pin	± 25	mA
P <sub>D</sub>	Power Dissipation in Still Air, SOIC Package† TSSOP Package†	500 450	mW
T <sub>stg</sub>	Storage Temperature	- 65 to + 150	°C
TL	Lead Temperature, 1 mm from Case for 10 Seconds	260	°C

†Derating — SOIC Package: – 7 mW/°C from 65° to 125°C TSSOP Package: – 6.1 mW/°C from 65° to 125°C

#### RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V <sub>CC</sub>	Positive DC Supply Voltage (Referenced to GND)	2.0	12.0	V
V <sub>IS</sub>	Analog Input Voltage (Referenced to GND)	GND	V <sub>CC</sub>	V
V <sub>in</sub>	Digital Input Voltage (Referenced to GND)	GND	V <sub>CC</sub>	V
V <sub>IO</sub> *	Static or Dynamic Voltage Across Switch		1.2	V
T <sub>A</sub>	Operating Temperature, All Package Types	- 55	+ 125	°C
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time, ON/OFF Control Inputs (Figure 14) $ \begin{array}{c} V_{CC} = 2.0 \text{ V} \\ V_{CC} = 3.0 \text{ V} \\ V_{CC} = 4.5 \text{ V} \\ V_{CC} = 9.0 \text{ V} \\ V_{CC} = 12.0 \text{ V} \end{array} $	0	1000 600 500 400 250	ns

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation,  $V_{in}$  and  $V_{out}$  should be constrained to the range GND  $\leq$  ( $V_{in}$  or  $V_{out}$ )  $\leq$   $V_{CC}$ .

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V<sub>CC</sub>). Unused outputs must be left open. I/O pins must be connected to a properly terminated line or bus.

<sup>\*</sup>For voltage drops across the switch greater than 1.2 V (switch on), excessive  $V_{CC}$  current may be drawn; i.e., the current out of the switch may contain both  $V_{CC}$  and switch input components. The reliability of the device will be unaffected unless the Maximum Ratings are exceeded.

## DC ELECTRICAL CHARACTERISTIC Digital Section (Voltages Referenced to GND)

				Gu	aranteed Li	mit	
Symbol	Parameter	Test Conditions	V <sub>CC</sub> V	– 55 to 25°C	≤ 85°C	≤ 125°C	Unit
V <sub>IH</sub>	Minimum High-Level Voltage ON/OFF Control Inputs	R <sub>on</sub> = Per Spec	2.0 3.0 4.5 9.0 12.0	1.5 2.1 3.15 6.3 8.4	1.5 2.1 3.15 6.3 8.4	1.5 2.1 3.15 6.3 8.4	V
V <sub>IL</sub>	Maximum Low-Level Voltage ON/OFF Control Inputs	R <sub>on</sub> = Per Spec	2.0 3.0 4.5 9.0 12.0	0.5 0.9 1.35 2.7 3.6	0.5 0.9 1.35 2.7 3.6	0.5 0.9 1.35 2.7 3.6	V
I <sub>in</sub>	Maximum Input Leakage Current ON/OFF Control Inputs	V <sub>in</sub> = V <sub>CC</sub> or GND	12.0	± 0.1	± 1.0	± 1.0	μА
Icc	Maximum Quiescent Supply Current (per Package)	$V_{in} = V_{CC}$ or GND $V_{IO} = 0$ V	6.0 12.0	2 4	20 40	40 160	μА

#### DC ELECTRICAL CHARACTERISTICS Analog Section (Voltages Referenced to GND)

				Gu	aranteed Li	mit	
Symbol	Parameter	Test Conditions	V <sub>CC</sub>	– 55 to 25°C	≤ 85°C	≤ 125°C	Unit
R <sub>on</sub>	Maximum "ON" Resistance	$\begin{split} &V_{in} = V_{IH} \\ &V_{IS} = V_{CC} \text{ to GND} \\ &I_{S} \leq 2.0 \text{ mA} \\ &(\text{Figures 2 through 7}) \end{split}$	2.0† 3.0† 4.5 9.0 12.0	— 120 70 70	 160 85 85	200 100 100	Ω
		$\begin{aligned} &V_{in} = V_{IH} \\ &V_{IS} = V_{CC} \text{ or GND (Endpoints)} \\ &I_{S} \leq 2.0 \text{ mA} \\ &(\text{Figures 2 through 7}) \end{aligned}$	2.0 3.0 4.5 9.0 12.0	— 70 50 30	— 85 60 60	— 100 80 80	
$\Delta R_{on}$	Maximum Difference in "ON" Resistance Between Any Two Channels in the Same Package	$\begin{aligned} &V_{\text{In}} = V_{\text{IH}} \\ &V_{\text{IS}} = 1/2 \; (V_{\text{CC}} - \text{GND}) \\ &I_{\text{S}} \leq 2.0 \; \text{mA} \end{aligned}$	2.0 4.5 9.0 12.0		25 20 20	— 30 25 25	Ω
l <sub>off</sub>	Maximum Off–Channel Leakage Current, Any One Channel	$V_{\text{in}} = V_{\text{IL}}$ $V_{\text{IO}} = V_{\text{CC}}$ or GND Switch Off	12.0	0.1	0.5	1.0	μА
I <sub>on</sub>	Maximum On–Channel Leakage Current, Any One Channel	$V_{\text{in}} = V_{\text{IH}}$ $V_{\text{IS}} = V_{\text{CC}}$ or GND	12.0	0.1	0.5	1.0	μА

<sup>†</sup>At supply voltage (V<sub>CC</sub>) approaching 3 V the analog switch-on resistance becomes extremely non-linear. Therefore, for low-voltage operation, it is recommended that these devices only be used to control digital signals.

# AC ELECTRICAL CHARACTERISTICS ( $C_L = 50 \text{ pF}$ , ON/OFF Control Inputs: $t_f = t_f = 6 \text{ ns}$ )

			Gu	aranteed Li	mit	
Symbol	Parameter	V <sub>CC</sub> V	– 55 to 25°C	≤ 85°C	≤ 125°C	Unit
t <sub>PLH</sub> , t <sub>PHL</sub>	Maximum Propagation Delay, Analog Input to Analog Output (Figures 18 and 13)	2.0 3.0 4.5 9.0 12.0	40 30 5 5 5	50 40 7 7 7	60 50 8 8 8	ns
t <sub>PLZ</sub> , t <sub>PHZ</sub>	Maximum Propagation Delay, ON/OFF Control to Analog Output (Figures 14 and 15)	2.0 3.0 4.5 9.0 12.0	80 60 20 20 20	90 70 25 25 25	110 80 35 35 35	ns
t <sub>PZL</sub> , t <sub>PZH</sub>	Maximum Propagation Delay, ON/OFF Control to Analog Output (Figures 14 and 15)	2.0 3.0 4.5 9.0 12.0	80 45 20 20 20	90 50 25 25 25	100 60 30 30 30	ns
С	Maximum Capacitance ON/OFF Control Input Control Input = GND Analog I/O Feedthrough	<u> </u>	10 35 1.0	10 35 1.0	10 35 1.0	pF
Con	Power Dissination Canacitance (Per Switch) (Figure 17)*		Typical	<b>@ 25°C, V<sub>C0</sub></b>	<sub>C</sub> = 5.0 V	nF

		Typical @ 25°C, V <sub>CC</sub> = 5.0 V	
$C_{PD}$	Power Dissipation Capacitance (Per Switch) (Figure 17)*	15	pF

<sup>\*</sup> Used to determine the no–load dynamic power consumption:  $P_D = C_{PD} \ V_{CC}^2 f + I_{CC} \ V_{CC}$ .

## ADDITIONAL APPLICATION CHARACTERISTICS (Voltages Referenced to GND Unless Noted)

Symbol	Parameter	Test Conditions	v <sub>cc</sub>	Limit* 25°C 74HC	Unit
BW	Maximum On–Channel Bandwidth or Minimum Frequency Response (Figure NO TAG)	$f_{in} = 1 \text{ MHz Sine Wave}$ Adjust $f_{in}$ Voltage to Obtain 0 dBm at $V_{OS}$ Increase $f_{in}$ Frequency Until dB Meter Reads $-3 \text{ dB}$ $R_L = 50 \ \Omega, \ C_L = 10 \text{ pF}$	4.5 9.0 12.0	150 160 160	MHz
_	Off-Channel Feedthrough Isolation (Figure NO TAG)	$\begin{split} f_{in} &\equiv \text{Sine Wave} \\ \text{Adjust } f_{in} &\text{ Voltage to Obtain 0 dBm at V}_{IS} \\ f_{in} &= 10 \text{ kHz}, \text{ R}_{L} = 600 \ \Omega, \text{ C}_{L} = 50 \text{ pF} \end{split}$	4.5 9.0 12.0	- 50 - 50 - 50	dB
		$f_{in}$ = 1.0 MHz, $R_L$ = 50 $\Omega$ , $C_L$ = 10 pF	4.5 9.0 12.0	- 40 - 40 - 40	
_	Feedthrough Noise, Control to Switch (Figure NO TAG)	$V_{in} \leq$ 1 MHz Square Wave ( $t_r = t_f = 6$ ns) Adjust R <sub>L</sub> at Setup so that I <sub>S</sub> = 0 A R <sub>L</sub> = 600 $\Omega$ , C <sub>L</sub> = 50 pF	4.5 9.0 12.0	60 130 200	mV <sub>PP</sub>
		$R_L = 10 \text{ k}\Omega$ , $C_L = 10 \text{ pF}$	4.5 9.0 12.0	30 65 100	
	Crosstalk Between Any Two Switches (Figure 16)	$ \begin{aligned} f_{in} &\equiv \text{Sine Wave} \\ \text{Adjust } f_{in} &\text{ Voltage to Obtain 0 dBm at V}_{IS} \\ f_{in} &= 10 \text{ kHz}, \text{ R}_{L} = 600 \ \Omega, \text{ C}_{L} = 50 \text{ pF} \end{aligned} $	4.5 9.0 12.0	- 70 - 70 - 70	dB
		$f_{in}$ = 1.0 MHz, $R_L$ = 50 $\Omega$ , $C_L$ = 10 pF	4.5 9.0 12.0	- 80 - 80 - 80	
THD	Total Harmonic Distortion (Figure 20)	$\begin{aligned} f_{in} &= 1 \text{ kHz}, \ R_L = 10 \text{ k}\Omega, \ C_L = 50 \text{ pF} \\ \text{THD} &= \text{THD}_{Measured} - \text{THD}_{Source} \\ V_{IS} &= 4.0 \text{ Vpp sine wave} \\ V_{IS} &= 8.0 \text{ Vpp sine wave} \\ V_{IS} &= 11.0 \text{ Vpp sine wave} \end{aligned}$	4.5 9.0 12.0	0.10 0.06 0.04	%

\*Guaranteed limits not tested. Determined by design and verified by qualification.

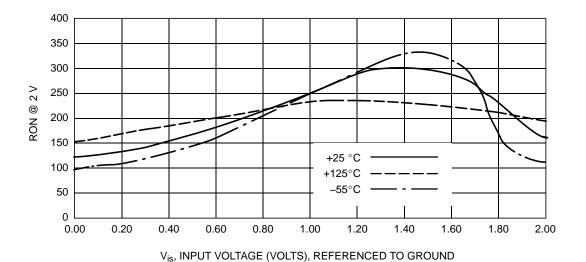
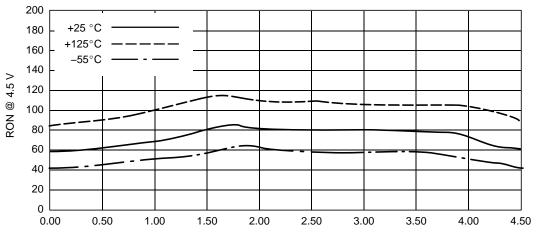


Figure 2. Typical On Resistance,  $V_{CC} = 2.0 \text{ V}$ 



 $V_{\text{is}}$ , INPUT VOLTAGE (VOLTS), REFERENCED TO GROUND

Figure 3. Typical On Resistance,  $V_{CC} = 4.5 \text{ V}$ 

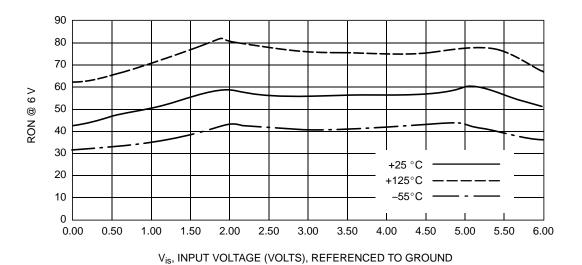


Figure 4. Typical On Resistance,  $V_{CC} = 6.0 \text{ V}$ 

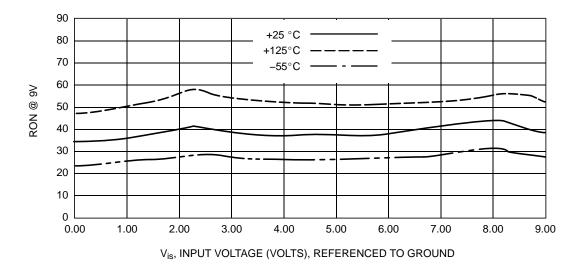


Figure 5. Typical On Resistance, V<sub>CC</sub> = 9.0 V

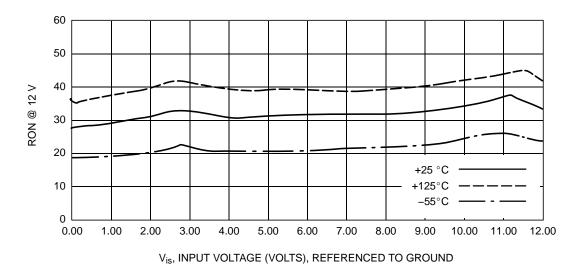


Figure 6. Typical On Resistance,  $V_{CC} = 12 \text{ V}$ 

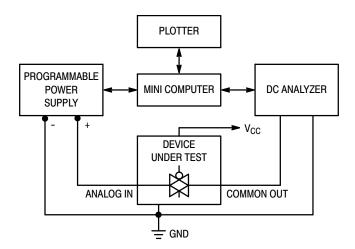


Figure 7. On Resistance Test Set-Up

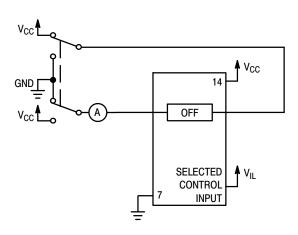


Figure 8. Maximum Off Channel Leakage Current, Any One Channel, Test Set-Up

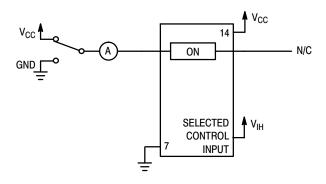
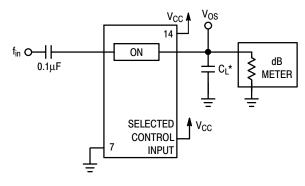


Figure 9. Maximum On Channel Leakage Current, Test Set-Up



\*Includes all probe and jig capacitance.

Figure 10. Maximum On-Channel Bandwidth
Test Set-Up

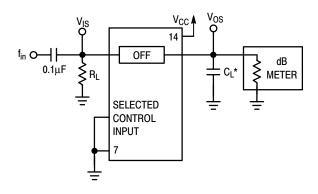
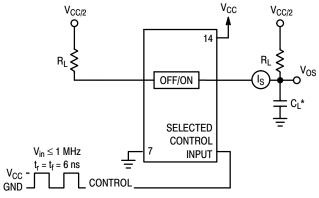


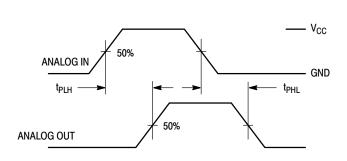
Figure 11. Off-Channel Feedthrough Isolation, Test Set-Up

\*Includes all probe and jig capacitance.



\*Includes all probe and jig capacitance.

Figure 12. Feedthrough Noise, ON/OFF Control to Analog Out, Test Set-Up



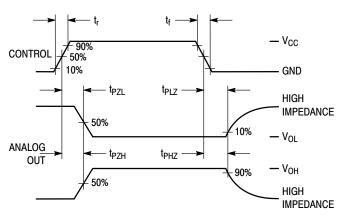
ANALOG IN ON ANALOG OUT TEST POINT

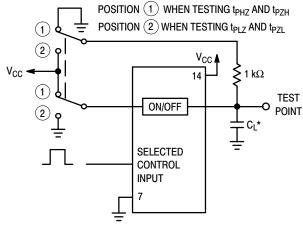
SELECTED CONTROL 7 INPUT

\*Includes all probe and jig capacitance.

Figure 18. Propagation Delays, Analog In to Analog Out

Figure 13. Propagation Delay Test Set-Up

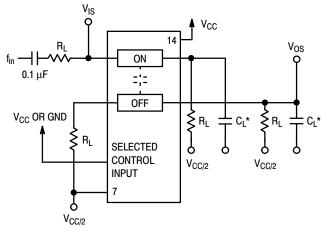




\*Includes all probe and jig capacitance.

Figure 14. Propagation Delay, ON/OFF Control to Analog Out

Figure 15. Propagation Delay Test Set-Up



\*Includes all probe and jig capacitance.

Figure 16. Crosstalk Between Any Two Switches, Test Set-Up

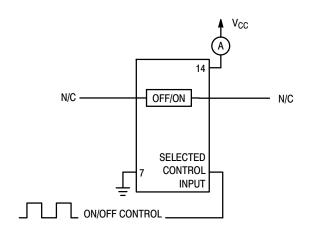
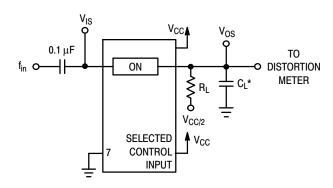


Figure 17. Power Dissipation Capacitance
Test Set-Up



\*Includes all probe and jig capacitance.

Figure 20. Total Harmonic Distortion, Test Set-Up

#### **APPLICATION INFORMATION**

The ON/OFF Control pins should be at  $V_{CC}$  or GND logic levels,  $V_{CC}$  being recognized as logic high and GND being recognized as a logic low. Unused analog inputs/outputs may be left floating (not connected). However, it is advisable to tie unused analog inputs and outputs to  $V_{CC}$  or GND through a low value resistor. This minimizes crosstalk and feedthrough noise that may be picked–up by the unused I/O pins.

The maximum analog voltage swings are determined by the supply voltages  $V_{CC}$  and GND. The positive peak analog voltage should not exceed  $V_{CC}$ . Similarly, the negative peak analog voltage should not go below GND. In

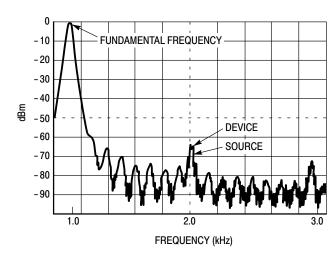


Figure 19. Plot, Harmonic Distortion

the example below, the difference between  $V_{CC}$  and GND is twelve volts. Therefore, using the configuration in Figure 21, a maximum analog signal of twelve volts peak–to–peak can be controlled.

When voltage transients above  $V_{CC}$  and/or below GND are anticipated on the analog channels, external diodes (Dx) are recommended as shown in Figure 22. These diodes should be small signal, fast turn–on types able to absorb the maximum anticipated current surges during clipping. An alternate method would be to replace the Dx diodes with Mosorbs (high current surge protectors). Mosorbs are fast turn–on devices ideally suited for precise DC protection with no inherent wear out mechanism.

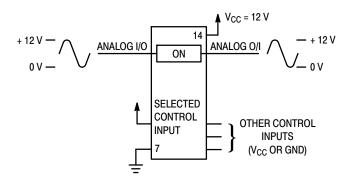


Figure 21. 12 V Application

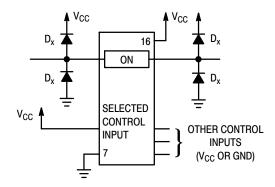


Figure 22. Transient Suppressor Application

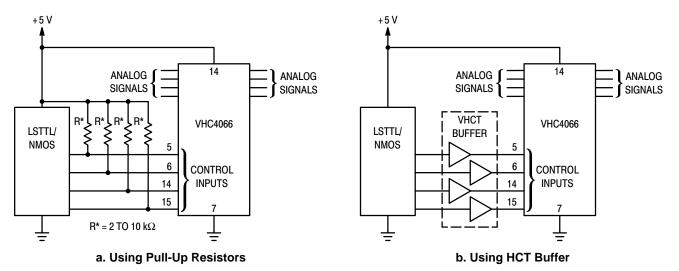


Figure 23. LSTTL/NMOS to HCMOS Interface

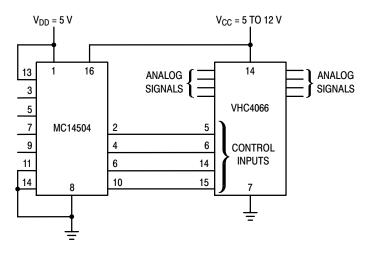


Figure 24. TTL/NMOS-to-CMOS Level Converter Analog Signal Peak-to-Peak Greater than 5 V (Also see VHC4316)

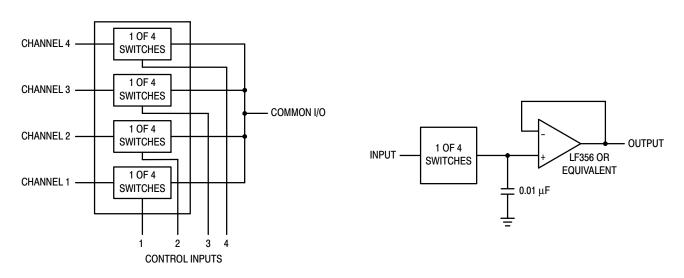


Figure 25. 4-Input Multiplexer

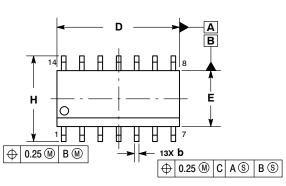
Figure 26. Sample/Hold Amplifier

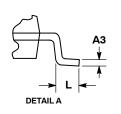


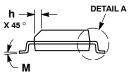
△ 0.10

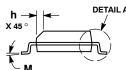
SOIC-14 NB CASE 751A-03 ISSUE L

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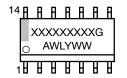




- NOTES:
  1. DIMENSIONING AND TOLERANCING PER
  - ASME Y14.5M, 1994.
    CONTROLLING DIMENSION: MILLIMETERS.
  - DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF AT
  - MAXIMUM MATERIAL CONDITION.
    DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSIONS.
- 5. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE

	MILLIMETERS INCHES		HES	
DIM	MIN	MAX	MIN	MAX
Α	1.35	1.75	0.054	0.068
A1	0.10	0.25	0.004	0.010
АЗ	0.19	0.25	0.008	0.010
b	0.35	0.49	0.014	0.019
D	8.55	8.75	0.337	0.344
Е	3.80	4.00	0.150	0.157
е	1.27	1.27 BSC		BSC
Н	5.80	6.20	0.228	0.244
h	0.25	0.50	0.010	0.019
L	0.40	1.25	0.016	0.049
M	0 °	7°	0 °	7 °

#### **GENERIC MARKING DIAGRAM\***



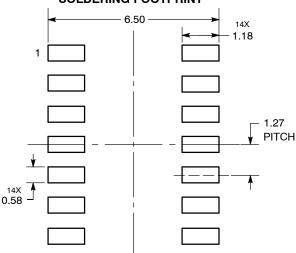
XXXXX = Specific Device Code Α = Assembly Location

WL = Wafer Lot Υ = Year = Work Week

WW = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

# **SOLDERING FOOTPRINT\***



DIMENSIONS: MILLIMETERS

C SEATING PLANE

#### **STYLES ON PAGE 2**

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DESCRIPTION:	SOIC-14 NB		PAGE 1 OF 2

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<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

### SOIC-14 CASE 751A-03 ISSUE L

## DATE 03 FEB 2016

STYLE 1: PIN 1. COMMON CATHODE 2. ANODE/CATHODE 3. ANODE/CATHODE 4. NO CONNECTION 5. ANODE/CATHODE 6. NO CONNECTION 7. ANODE/CATHODE 8. ANODE/CATHODE 9. ANODE/CATHODE 10. NO CONNECTION 11. ANODE/CATHODE 12. ANODE/CATHODE 13. NO CONNECTION 14. COMMON ANODE	STYLE 2: CANCELLED	STYLE 3: PIN 1. NO CONNECTION 2. ANODE 3. ANODE 4. NO CONNECTION 5. ANODE 6. NO CONNECTION 7. ANODE 8. ANODE 9. ANODE 10. NO CONNECTION 11. ANODE 12. ANODE 13. NO CONNECTION 14. COMMON CATHODE	STYLE 4: PIN 1. NO CONNECTION 2. CATHODE 3. CATHODE 4. NO CONNECTION 5. CATHODE 6. NO CONNECTION 7. CATHODE 8. CATHODE 9. CATHODE 10. NO CONNECTION 11. CATHODE 12. CATHODE 13. NO CONNECTION 14. COMMON ANODE
STYLE 5: PIN 1. COMMON CATHODE 2. ANODE/CATHODE 3. ANODE/CATHODE 4. ANODE/CATHODE 5. ANODE/CATHODE 6. NO CONNECTION 7. COMMON ANODE 8. COMMON CATHODE 9. ANODE/CATHODE 10. ANODE/CATHODE 11. ANODE/CATHODE 12. ANODE/CATHODE 13. NO CONNECTION 14. COMMON ANODE	STYLE 6: PIN 1. CATHODE 2. CATHODE 3. CATHODE 4. CATHODE 5. CATHODE 6. CATHODE 7. CATHODE 8. ANODE 9. ANODE 10. ANODE 11. ANODE 12. ANODE 13. ANODE 14. ANODE	STYLE 7: PIN 1. ANODE/CATHODE 2. COMMON ANODE 3. COMMON CATHODE 4. ANODE/CATHODE 5. ANODE/CATHODE 6. ANODE/CATHODE 7. ANODE/CATHODE 8. ANODE/CATHODE 9. ANODE/CATHODE 10. ANODE/CATHODE 11. COMMON CATHODE 12. COMMON ANODE 13. ANODE/CATHODE 14. ANODE/CATHODE	STYLE 8: PIN 1. COMMON CATHODE 2. ANODE/CATHODE 3. ANODE/CATHODE 4. NO CONNECTION 5. ANODE/CATHODE 6. ANODE/CATHODE 7. COMMON ANODE 8. COMMON ANODE 9. ANODE/CATHODE 10. ANODE/CATHODE 11. NO CONNECTION 12. ANODE/CATHODE 13. ANODE/CATHODE 14. COMMON CATHODE

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